SN54298, SN54LS298, SN74298, SN74LS298
QUADRUPLE 2-INPUT MULTIPLEXERS WITH STORAGE

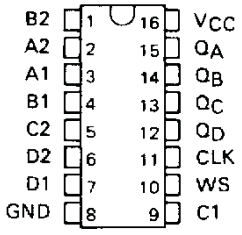
SDLS098 MARCH 1974 – REVISED MARCH 1988

- **Selects One of Two 4-Bit Data Sources and Stores Data Synchronously with System Clock**
- **Applications:**
  Dual Source for Operands and Constants in Arithmetic Processor; Can Release Processor Register Files for Acquiring New Data

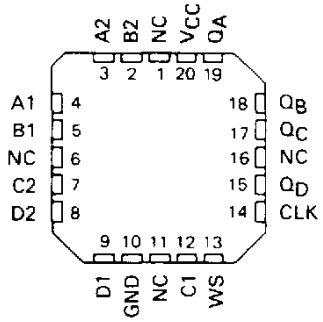
  Implement Separate Registers Capable of Parallel Exchange of Contents Yet Retain External Load Capability

  Universal Type Register for Implementing Various Shift Patterns; Even Has Compound Left-Right Capabilities

SN54298, SN54LS298 . . . J OR W PACKAGE
SN74298 . . . N PACKAGE
SN74LS298 . . . D OR N PACKAGE
(TOP VIEW)



SN54LS298 . . . FK PACKAGE
(TOP VIEW)



NC - No internal connection

description

These monolithic quadruple two-input multiplexers with storage provide essentially the equivalent functional capabilities of two separate MSI functions (SN54157/SN74157 or SN54LS157/SN74LS157 and SN54175/SN74175 or SN54LS175/SN74LS175) in a single 16-pin package.

When the word-select input is low, word 1 (A1, B1, C1, D1) is applies to the flip-flops. A high input to word select will cause the selection of word 2 (A2, B2, C2, D2). The selected word is clocked to the output terminals on the negative-going edge of the clock pulse.

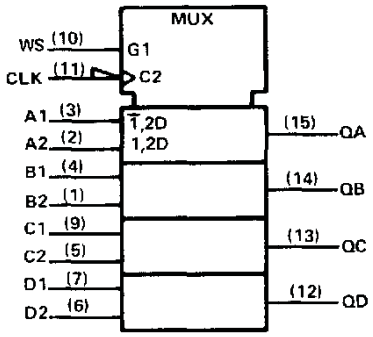
Typical power dissipation is 195 milliwatts for the '298 and 65 milliwatts for the 'LS298. SN54298 and SN54LS298 are characterized for operation over the full military temperature range of −55°C to 125°C; SN74298 and SN74LS298 are characterized for operation from 0°C to 70°C.

FUNCTION TABLE

INPUTS		OUTPUTS			
WORD SELECT	CLOCK	Q_A	Q_B	Q_C	Q_D
L	↓	a1	b1	c1	d1
H	↓	a2	b2	c2	d2
X	H	Q_{A0}	Q_{B0}	Q_{C0}	Q_{D0}

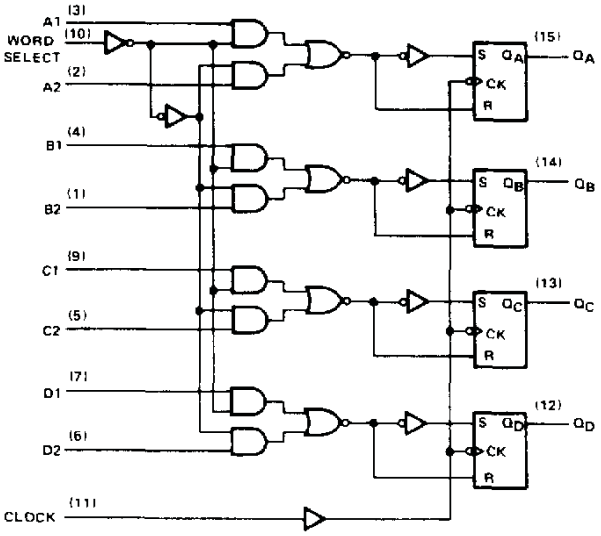
H = high level (steady state)
L = low level (steady state)
X = irrelevant (any input, including transitions)
↓ = transition from high to low level
a1, a2, etc. = the level of steady state input at A1, A2, etc.
Q_{A0}, Q_{B0}, etc. = the level of Q_A, Q_B, etc. entered on the most recent ↓ transition of the clock input.

logic symbol†



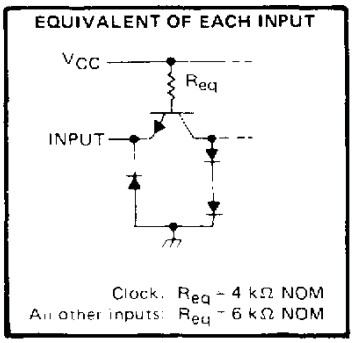
†This symbol is in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.
Pin numbers shown are for D, J, N, and W packages.

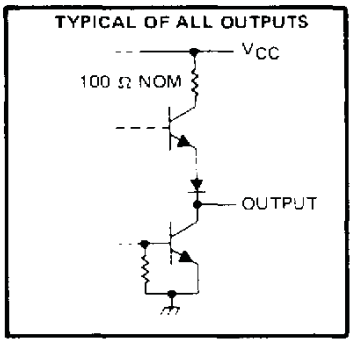
logic diagram (positive logic)



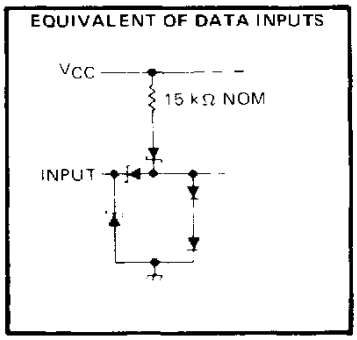
schematics of inputs and outputs

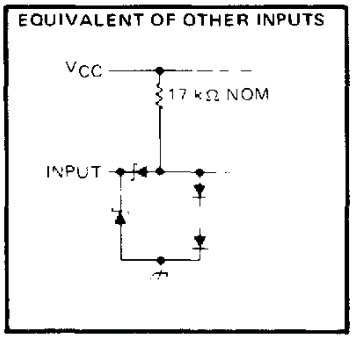
'298

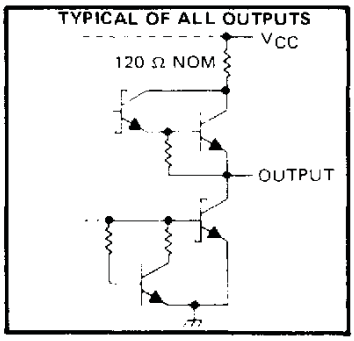




'LS298







absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V_{CC} (see Note 1) . . . . . 7 V
Input voltage . . . . . 5.5 V
Operating free-air temperature range: SN54298 . . . . . −55°C to 125°C
SN74298 . . . . . 0°C to 70°C
Storage temperature . . . . . −65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

recommended operating conditions

		SN54298			SN74298			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
Supply voltage, V_{CC}		4.5	5	5.5	4.75	5	5.25	V
High-level output current, I_{OH}				−800			−800	μA
Low-level output current, I_{OL}				16			16	mA
Width of clock pulse, high or low level, t_w		20			20			ns
Setup time, t_{su}	Data	15			15			ns
	Word select	25			25			
Hold time, t_h	Data	5			5			ns
	Word select	0			0			
Operating free-air temperature, T_A		−55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS†		MIN	TYP‡	MAX	UNIT
V_{IH}	High-level input voltage			2			V
V_{IL}	Low-level input voltage					0.8	V
V_{IK}	Input clamp voltage	V_{CC} = MIN, I_I = −12 mA				−1.5	V
V_{OH}	High-level output voltage	V_{CC} = MIN, V_{IH} = 2 V, V_{IL} = 0.8 V, I_{OH} = −800 μA		2.4	3.2		V
V_{OL}	Low-level output voltage	V_{CC} = MIN, V_{IH} = 2 V, V_{IL} = 0.8 V, I_{OL} = 16 mA				0.4	V
I_I	Input current at maximum input voltage	V_{CC} = MAX, V_I = 5.5 V				1	mA
I_{IH}	High-level input current	V_{CC} = MAX, V_I = 2.4 V				40	μA
I_{IL}	Low-level input current	V_{CC} = MAX, V_I = 0.4 V				−1.6	mA
I_{OS}	Short-circuit output current§	V_{CC} = MAX	SN54298	−20		−57	mA
			SN74298	−18		−57	
I_{CC}	Supply current	V_{CC} = MAX, See Note 2			39	65	mA

†For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.
‡All typical values are at V_{CC} = 5 V, T_A = 25°C.
§Not more than one output should be shorted at a time.
NOTE 2: With all outputs open and all inputs except clock low, I_{CC} is measured after applying a momentary 4.5 V, followed by ground, to the clock input.

switching characteristics, V_{CC} = 5 V, T_A = 25°C

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PLH}	Propagation delay time, low-to-high-level output	C_L = 15 pF, R_L = 400 Ω, See Note 3		18	27	ns
t_{PHL}	Propagation delay time, high-to-low-level output			21	32	

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V_{CC} (see Note 1) . . . . . 7 V
Input voltage . . . . . 7 V
Operating free-air temperature range: SN54LS298 . . . . . −55°C to 125°C
SN74LS298 . . . . . 0°C to 70°C
Storage temperature range . . . . . −65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

recommended operating conditions

		SN54LS298			SN74LS298			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
Supply voltage, V_{CC}		4.5	5	5.5	4.75	5	5.25	V
High-level output current, I_{OH}				−400			−400	μA
Low-level output current, I_{OL}				4			8	mA
Width of clock pulse, high or low level, t_w		20			20			ns
Setup time, t_{su}	Data	15			15			ns
	Word select	25			25			
Hold time, t_h	Data	5			5			ns
	Word select	0			0			
Operating free-air temperature, T_A		−55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS†		SN54LS298			SN74LS298			UNIT
				MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V_{IH}	High-level input voltage			2			2			V
V_{IL}	Low-level input voltage					0.7			0.8	V
V_{IK}	Input clamp voltage	V_{CC} = MIN, I_I = −18 mA				−1.5			−1.5	V
V_{OH}	High-level output voltage	V_{CC} = MIN, V_{IH} = 2 V, V_{IL} = V_{IL} max, I_{OH} = −400 μA		2.5	3.4		2.7	3.4		V
V_{OL}	Low-level output voltage	V_{CC} = MIN, V_{IH} = 2 V, V_{IL} = V_{IL} max	I_{OL} = 4 mA		0.25	0.4		0.25	0.4	V
			I_{OL} = 8 mA					0.35	0.5	
I_I	Input current at maximum input voltage	V_{CC} = MAX, V_I = 7 V				0.1			0.1	mA
I_{IH}	High-level input current	V_{CC} = MAX, V_I = 2.7 V				20			20	μA
I_{IL}	Low-level input current	V_{CC} = MAX, V_I = 0.4 V				−0.4			−0.4	mA
I_{OS}	Short-circuit output current§	V_{CC} = MAX		−20		−100	−20		−100	mA
I_{CC}	Supply current	V_{CC} = MAX, See Note 2			13	21		13	21	mA

†For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.
‡All typical values are at V_{CC} = 5 V, T_A = 25°C.
§Not more than one output should be shorted at a time, and duration of the short-circuit should not exceed one second.
NOTE 2: With all outputs open and all inputs except clock low, I_{CC} is measured after applying a momentary 4.5 V, followed by ground, to the clock input.

switching characteristics, V_{CC} = 5 V, T_A = 25°C

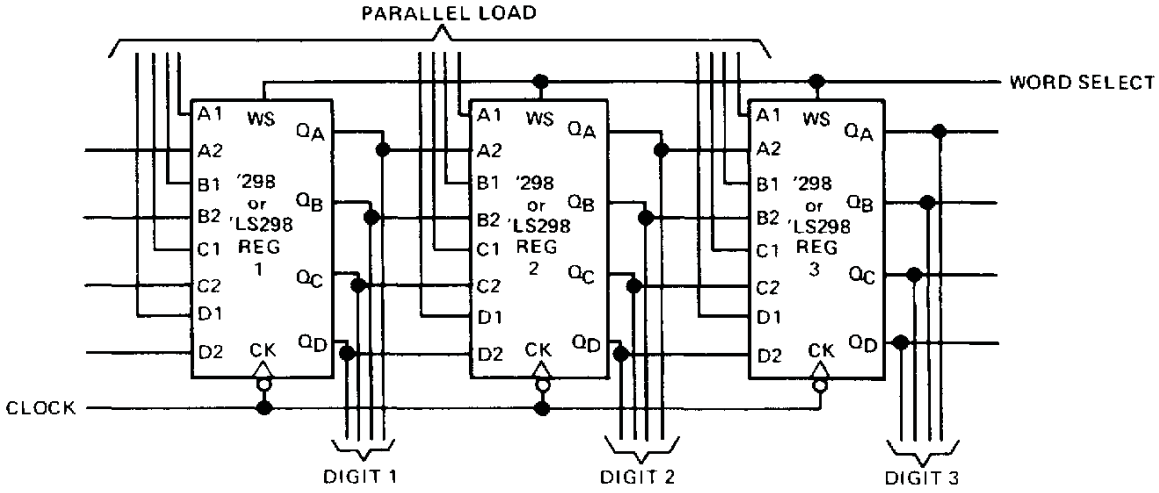
PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PLH}	Propagation delay time, low-to-high-level output	C_L = 15 pF, R_L = 2 kΩ, See Note 3		18	27	ns
t_{PHL}	Propagation delay time, high-to-low-level output			21	32	

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.

TYPICAL APPLICATION DATA

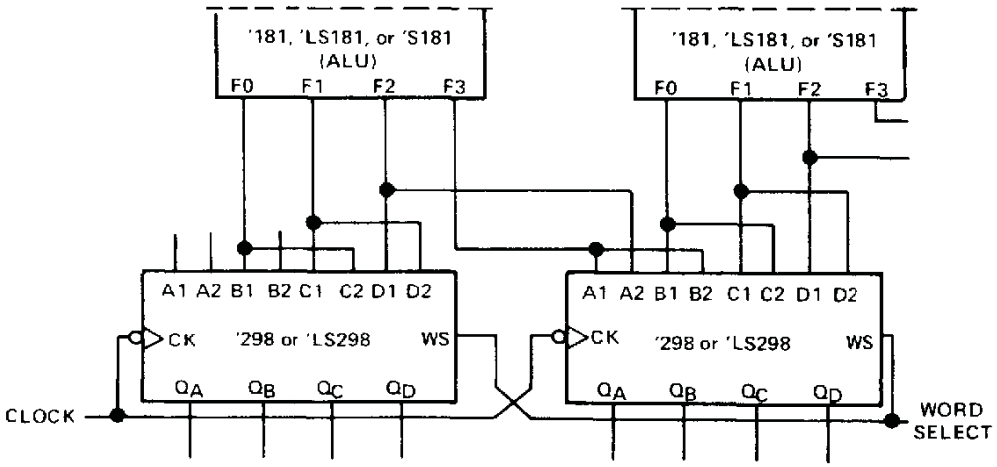
This versatile multiplexer/register can be connected to operate as a shift register that can shift N-places in a single clock pulse.

The following figure illustrates a BCD shift register that will shift an entire 4-bit BCD digit in one clock pulse.



When the word-select input is high and the registers are clocked, the contents of register 1 is transferred (shifted) to register 2 and etc. In effect, the BCD digits are shifted one position. In addition, this application retains a parallel-load capability which means that new BCD data can be entered in the entire register with one clock pulse. This arrangement can be modified to perform the shifting of binary data for any number of bit locations.

Another function that can be implemented with the '298 or 'LS298 is a register that can be designed specifically for supporting multiplier or division operations. The example below is a one place/two-place shift register.



When word select is low and the register is clocked, the outputs of the arithmetic/logic units (ALU's) are shifted one place. When word select is high and the registers are clocked, the data is shifted two places.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)
7601901EA	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
7601901FA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
7601901FA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
SN54298J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI
SN54298J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI
SN54LS298J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SN54LS298J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SN74298N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74298N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74298N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74298N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74LS298D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS298D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS298DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS298DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS298DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS298DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS298DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS298DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS298N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS298N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS298N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74LS298N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74LS298NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS298NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SNJ54298J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI
SNJ54298J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI
SNJ54298W	OBSOLETE	CFP	W	16		TBD	Call TI	Call TI
SNJ54298W	OBSOLETE	CFP	W	16		TBD	Call TI	Call TI
SNJ54LS298FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS298FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS298J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54LS298J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54LS298W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type

Orderable Device	Status [1]	Package Type	Package Drawing	Pins	Package Qty	Eco Plan [2]	Lead/Ball Finish	MSL Peak Temp [3]
SNJ54LS298W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type

[1] The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

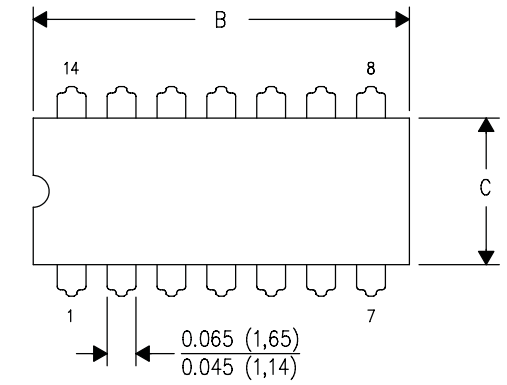
[2] Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

[3] MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

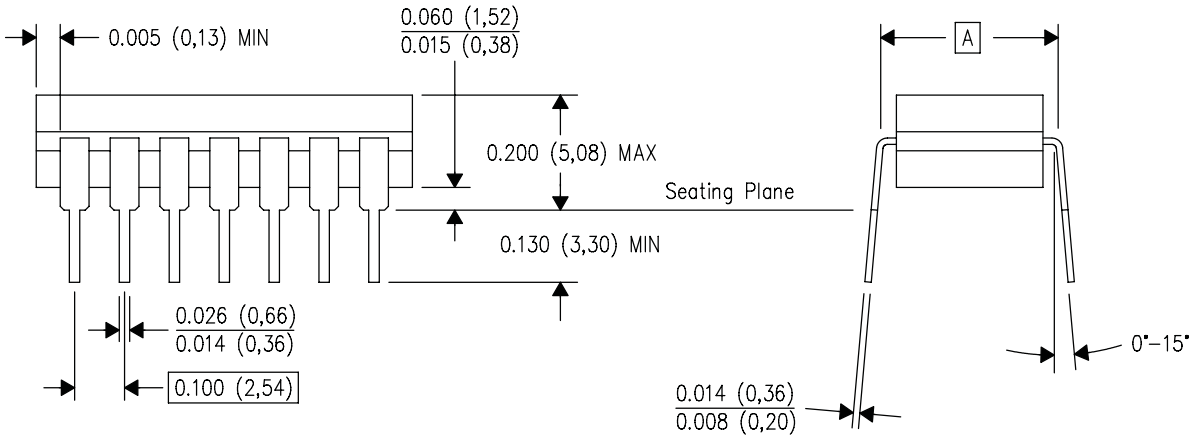
J (R–GDIP–T**)

14 LEADS SHOWN

CERAMIC DUAL IN–LINE PACKAGE



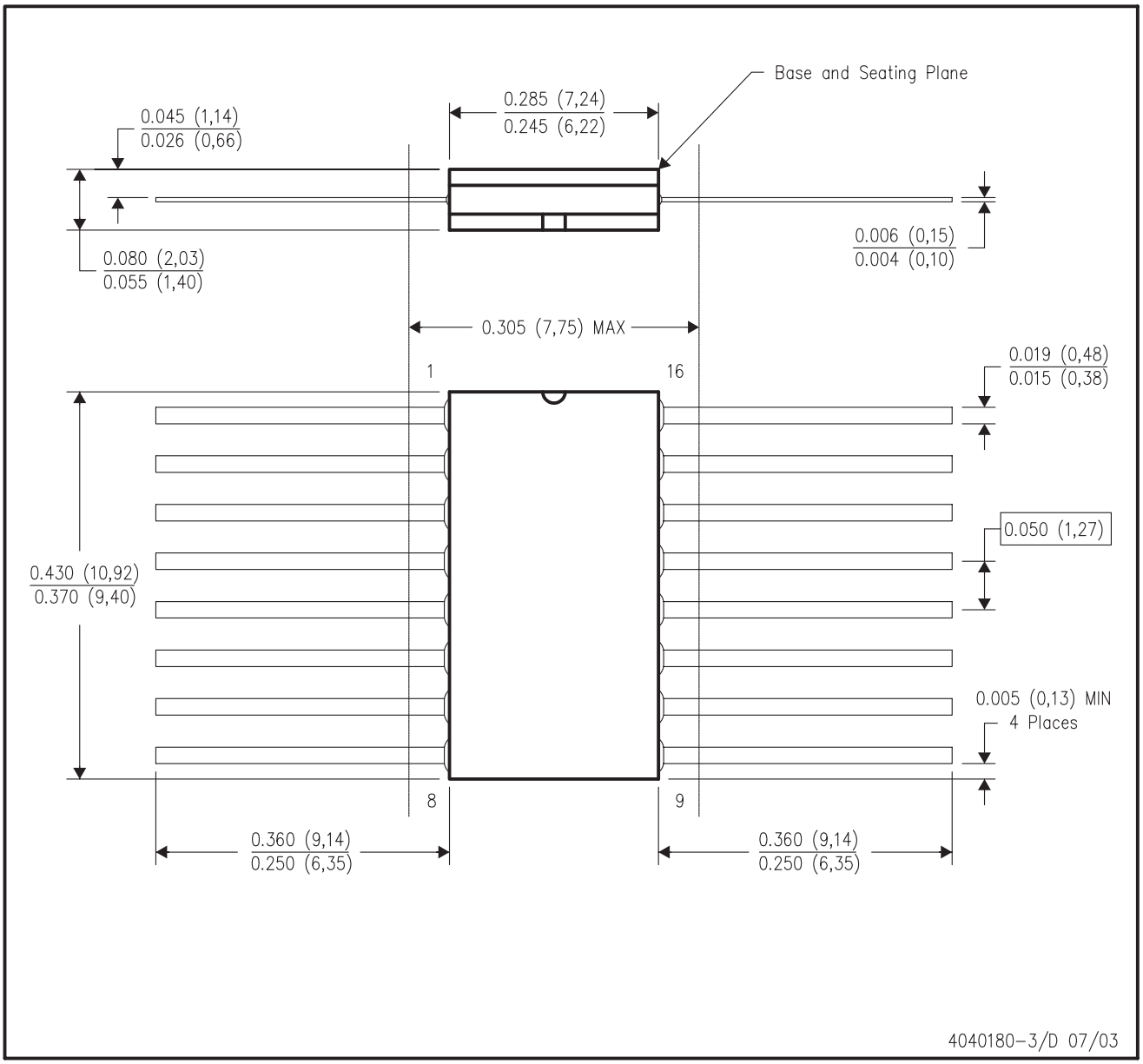
DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package is hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
E. Falls within MIL STD 1835 GDIP1–T14, GDIP1–T16, GDIP1–T18 and GDIP1–T20.

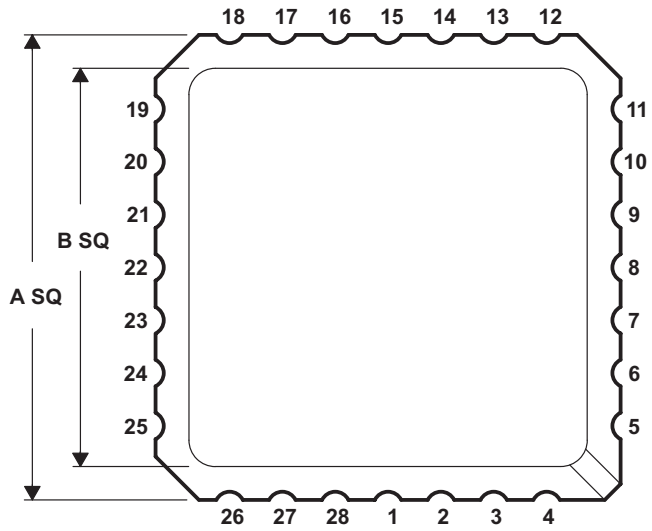
W (R–GDFP–F16) CERAMIC DUAL FLATPACK



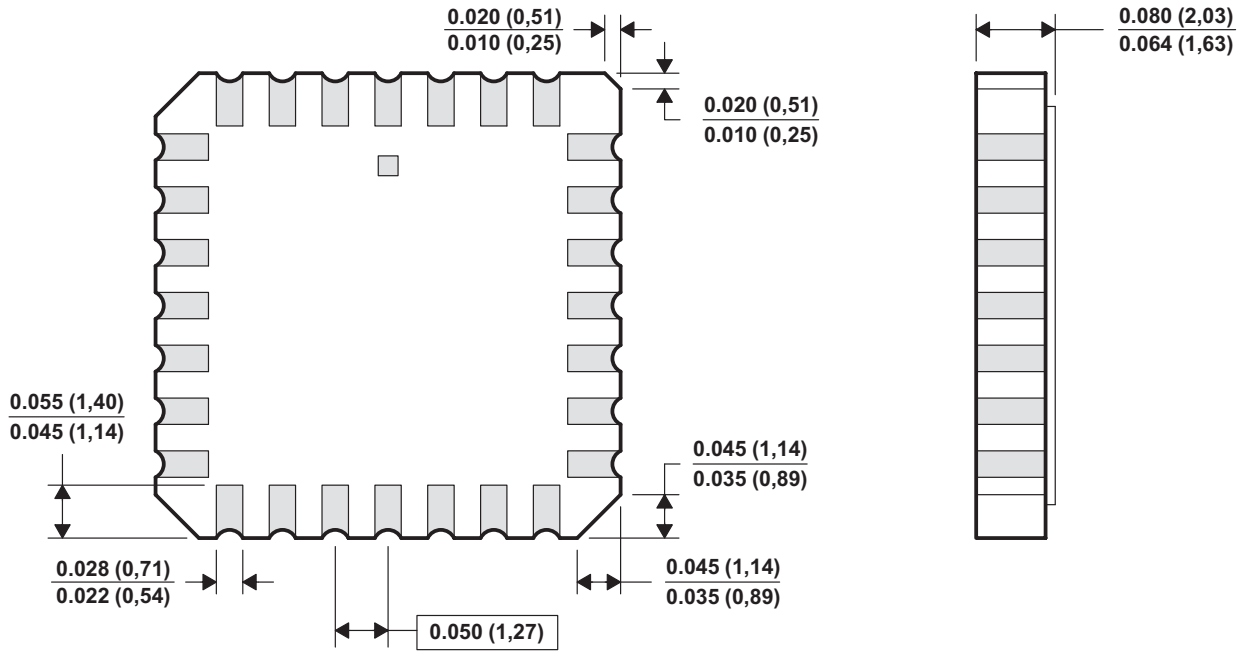
NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only.
E. Falls within MIL STD 1835 GDFP1–F16 and JEDEC MO–092AC

FK (S-CQCC-N)** **LEADLESS CERAMIC CHIP CARRIER**

28 TERMINAL SHOWN



NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.739 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)



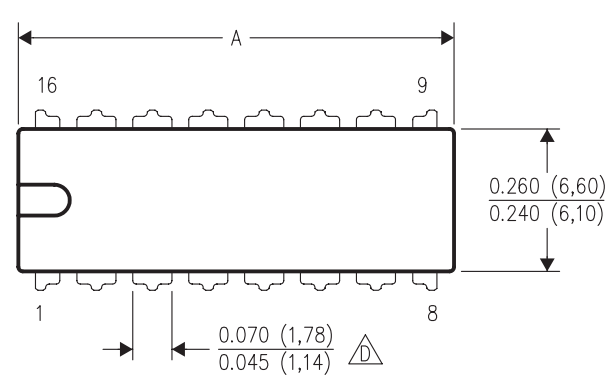
4040140/D 10/96

NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a metal lid.
D. The terminals are gold plated.
E. Falls within JEDEC MS-004

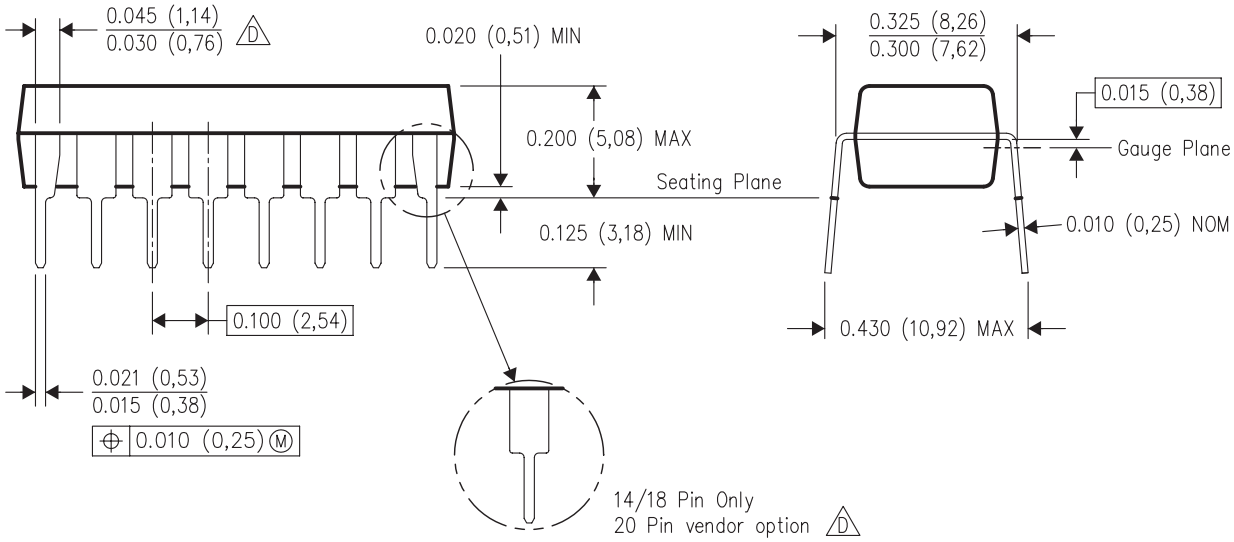
N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN



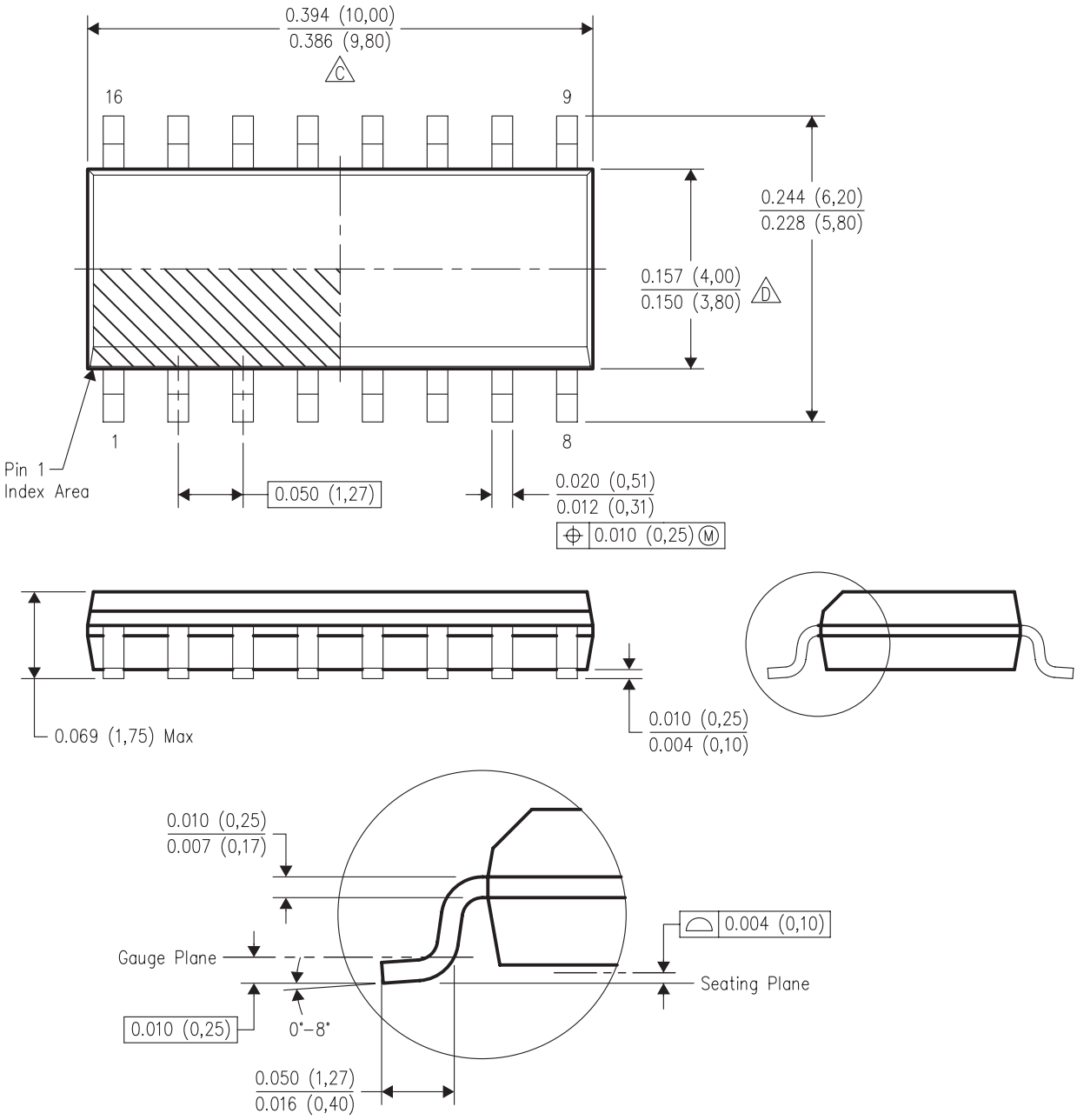
DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS–001 VARIATION (C)	AA	BB	AC	AD



4040049/E 12/2002

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R–PDSO–G16) PLASTIC SMALL–OUTLINE PACKAGE



NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
D. Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
E. Reference JEDEC MS–012 variation AC.

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